



Benefits of SiC for Industrial Auxilliary Power Supply

14.06.2018

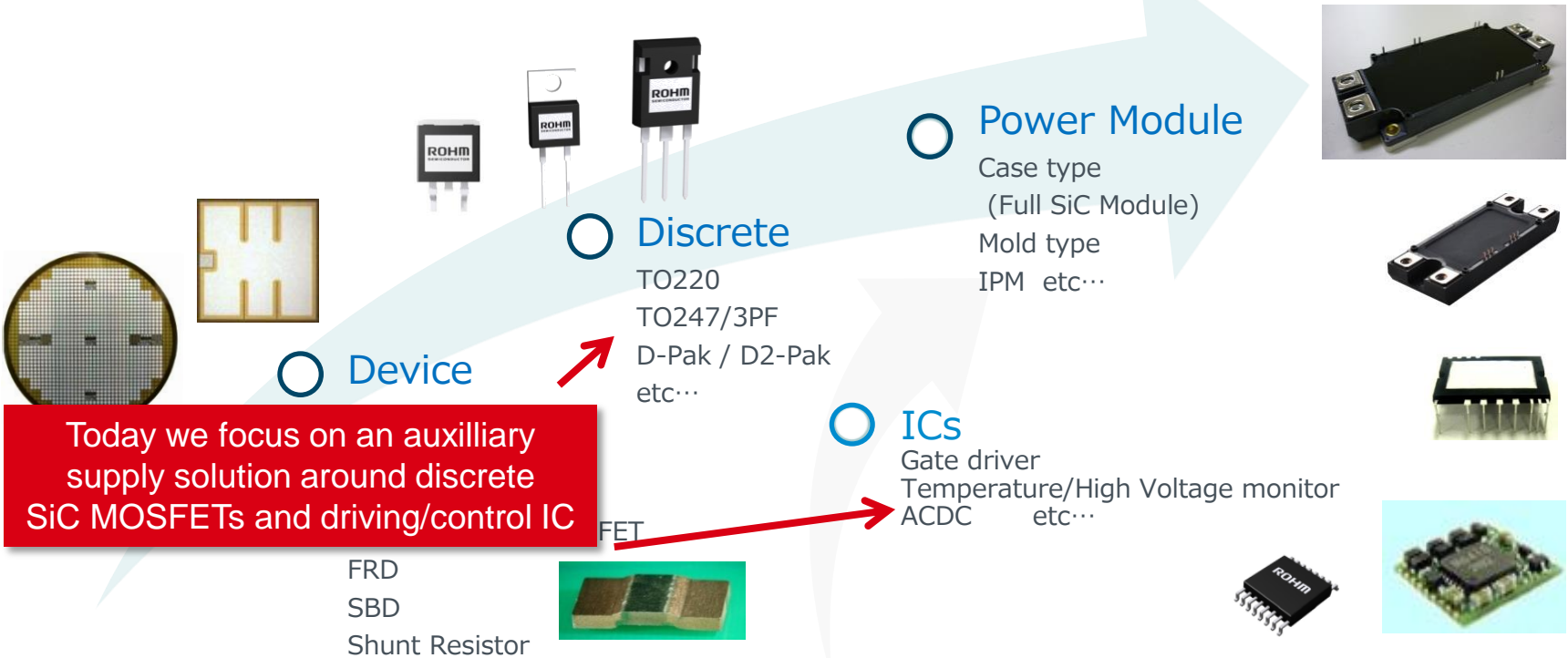
Dr.-Ing. Christian Felgemacher

Application Engineer – Power Systems Department

ROHM's Power Devices

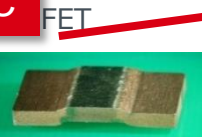


ROHM's power item lineup covers wafers/bare dies, discrete packages, module, ICs and Intelligent Power Modules



○ Device

- FRD
- SBD
- Shunt Resistor



○ Discrete

- TO220
- TO247/3PF
- D-Pak / D2-Pak etc...

○ ICs

- Gate driver
- Temperature/High Voltage monitor
- ACDC etc...

○ Power Module

- Case type (Full SiC Module)
- Mold type
- IPM etc...

Today we focus on an auxiliary supply solution around discrete SiC MOSFETs and driving/control IC

Integrated SiC Production

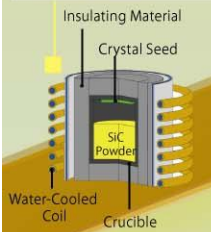


Stable supply

High quality



Advanced crystal technology
Temperature: 2000-2400°C
(Silicon: 1230-1260°C)
Principle: Recrystallization is performed whereby sublimated gas is transported to the surface of the seed crystal at high temperature based on the thermal gradient.



SiC Ingot



Wafer Production

SiC Wafer Production
Development and production performed at SiCrystal, a ROHM Group Company, in Nurnberg, Germany.



Wafer Process
SiC processes



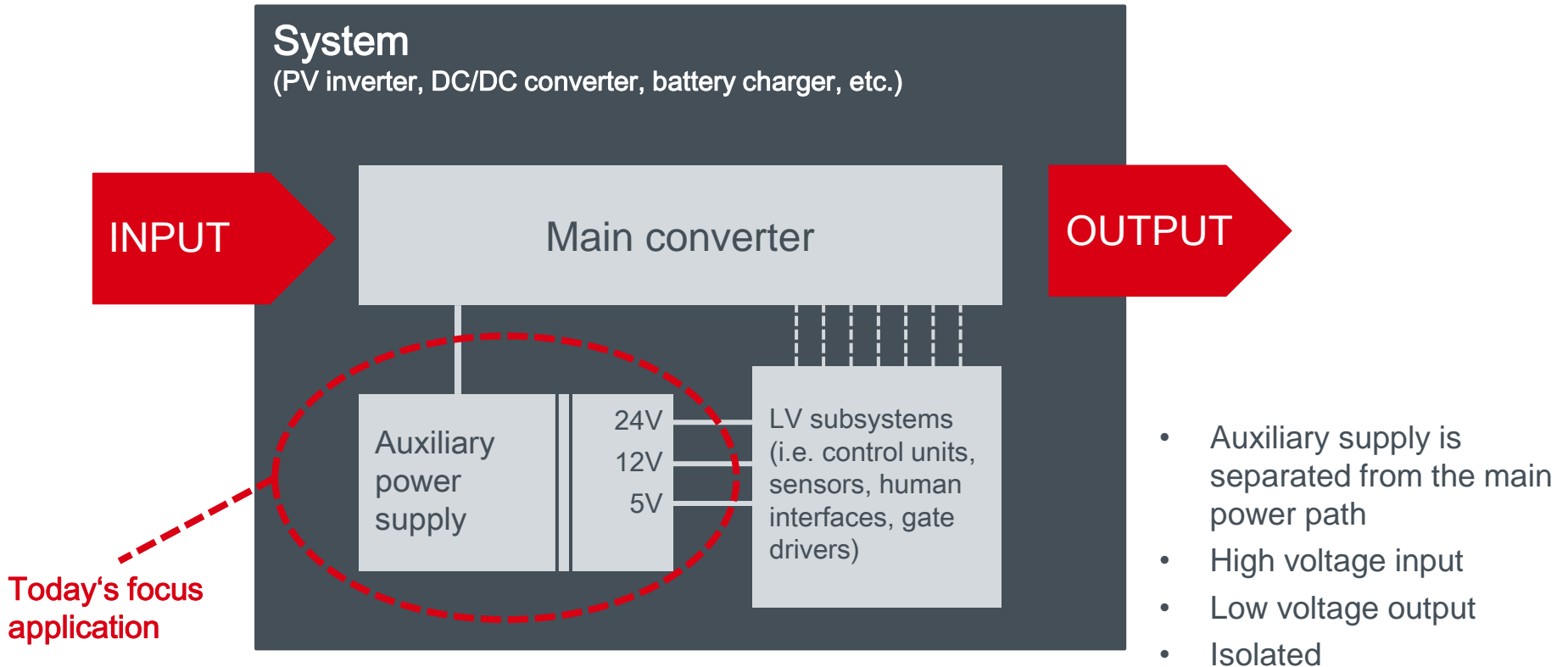
Assembly Line
In-house production equipment

Manufacturing system developed in-house

Our production system, developed completely in-house, enables us to quickly meet customer needs.



Auxiliary power supplies for industrial applications



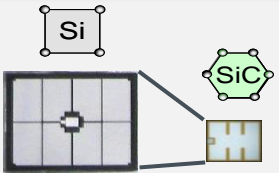
Expensive



Device cost may be higher, but **overall system cost equal or lower**

Application advantages vs. Si components

Lower Resistance



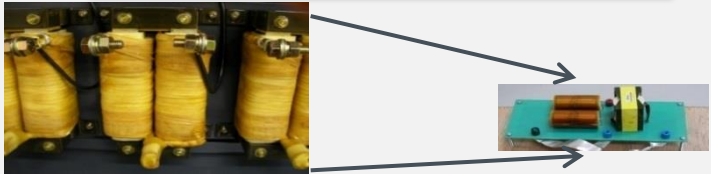
Smaller Size / Higher Efficiency



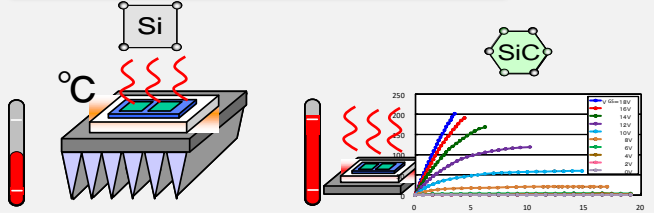
Higher Frequency Operation



Smaller Passive Components



Higher Temp Operation



Simpler Cooling System



Myths of SiC MOSFET technology

Expensive



Device cost may be higher, but **overall system cost equal or lower**

Not reliable



Extensive reliability testing done, comparable to Si-based devices

Reliability aspects of SiC Trench MOSFETs

Reliability tests for ROHM Trench MOSFETs

Test	IEC Standard	Conditions	Si	SiC	Comments SiC
<u>H</u> igh <u>T</u> emperature <u>R</u> everse <u>B</u> ias	60747	1000 h @ 95% $V_{ds,max}$, $T_{amb} = 125..145^{\circ}C$	✓	✓	@ 100% $V_{ds,max}$ $T_{amb} = T_{j,max} = 175^{\circ}C$
<u>H</u> igh <u>T</u> emperature <u>G</u> ate <u>B</u> ias	60747	1000 h @ $\pm V_{GS,max}$	✓	✓	
<u>H</u> igh <u>H</u> umidity <u>H</u> igh <u>T</u> emperature <u>R</u> everse <u>B</u> ias	60747				$V_{ds,max} = 100V$
<u>H</u> igh <u>T</u> emperature <u>S</u> torage	60747				
<u>L</u> ow <u>T</u> emperature <u>S</u> torage	60068-2-1	1000 h @ $T_{STG,min}$	✓	✓	
<u>T</u> hermal <u>C</u> ycle	60068-2-14	100 cycles $T_{STG,max} - T_{STG,min}$	✓	✓	

SiC 3 Gen. MOSFETs undergo reliability tests similar to those for Si MOSFETs and IGBTs
→ Automotive qualification soon to be finished

Myths of SiC MOSFET technology

Expensive



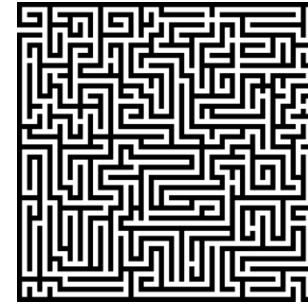
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Complex



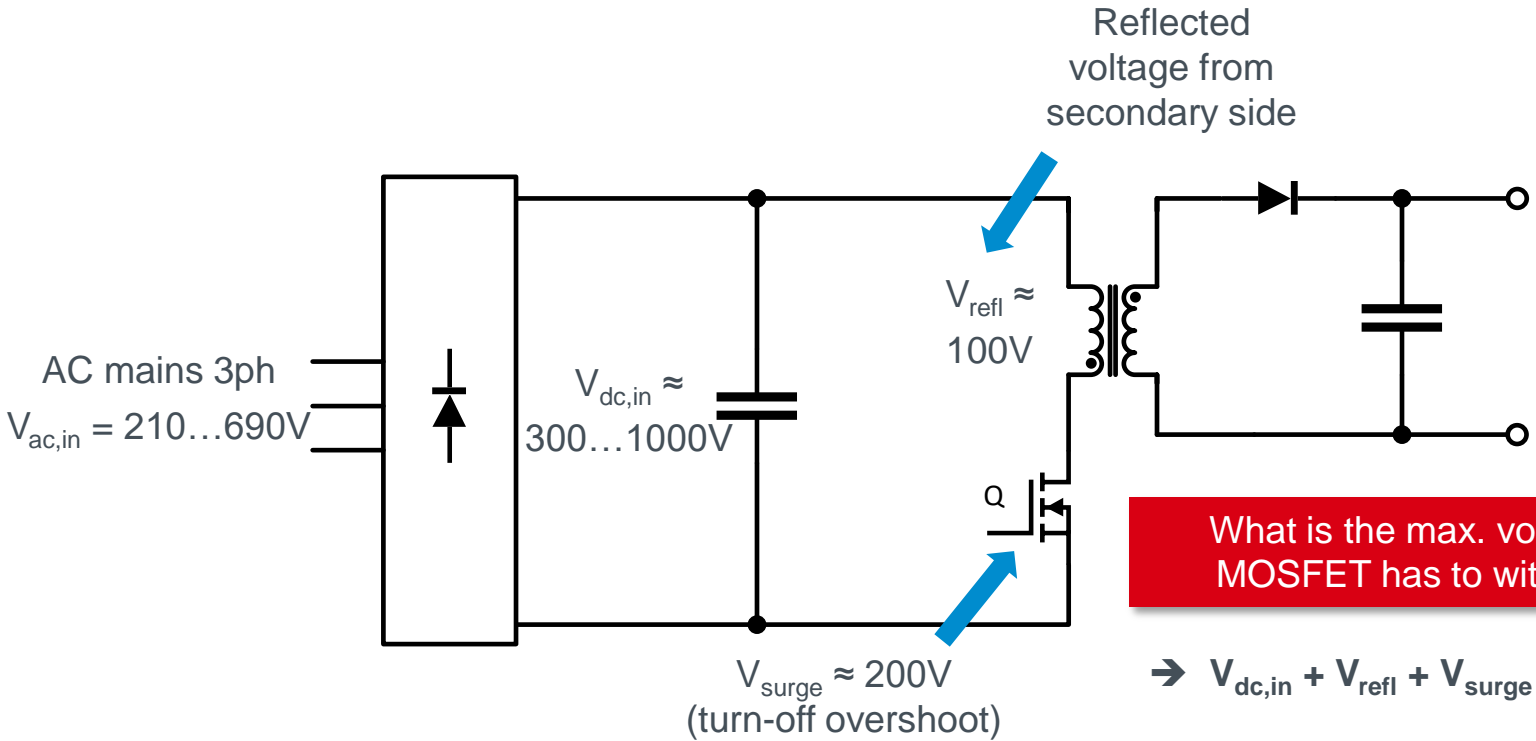
Use of SiC MOSFETs can simplify circuit design



Today's focus:
Simple solution for aux supply

Typical circuit for industrial auxilliary supply

Flyback converter with 3-phase input

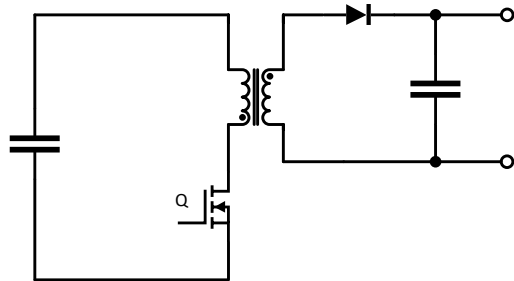


What is the max. voltage the MOSFET has to withstand?

→ $V_{dc,in} + V_{refl} + V_{surge} = 1300V$

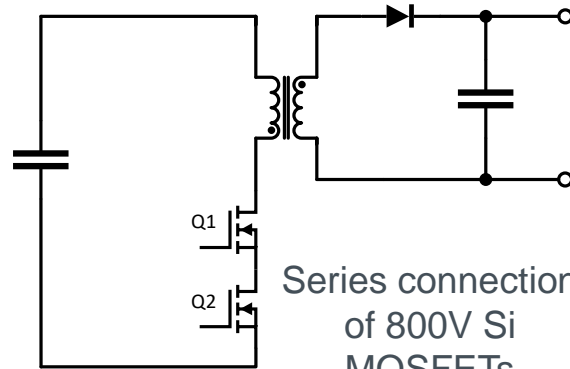
Device rated voltage: $\geq 1500 V$

Typical Si-based solutions



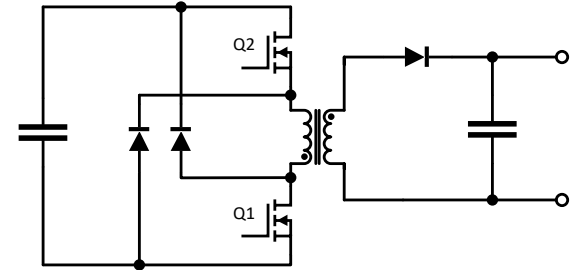
1500V Si MOSFET
e.g. 1500V, 6Ω

- High gate charge Q_g (high gate driving losses)
- High leakage current, especially at high temp.
- High conduction losses



Series connection
of 800V Si
MOSFETs

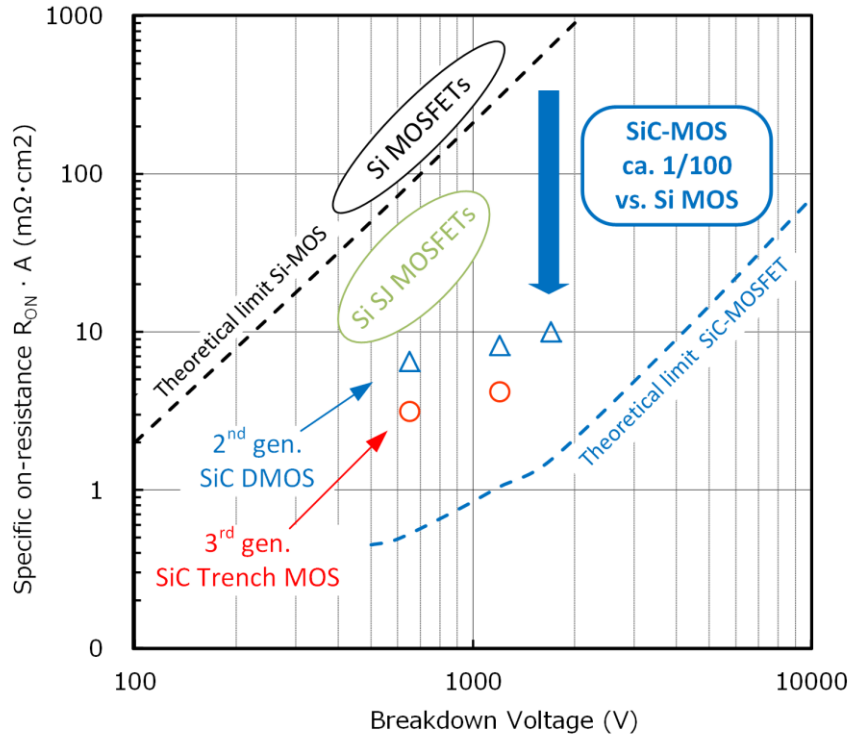
- Gate driving circuit more complex
- Static voltage balancing network
- Larger space for the heat sink



Two-switch flyback
topology

- Higher complexity in design and assembly
- Isolated gate driver & power supply for high side
- Larger space for the heat sink

Why use a SiC-MOSFET in this application?



Technology advantage of SiC MOSFET:

→ Significantly reduced $R_{DS(on)} \cdot A$

Why use a SiC-MOSFET in this application?



Property	unit	SCT2H12NZ			Si-MOSFET-A			Si-MOSFET-B			Si-MOSFET-C		
		min	typ	max	min	typ	max	min	typ	max	min	typ	max
V(BR)DSS	V	1700			1500			1500			1500		
I _d @ 25°C	A		3,7				2			2,5			6
R _{ds(on)} @25°C	Ω		1,15	1,5		9	12		6	9		2,2	3
I _{dss} @25°C	μA		0,1	10			500			10			1000
C _{iss}	pF		184			990			939			2025	
R _g	Ω		64						4				
Q _g	nC		14						29,3			114	
R _{th(j-c)}	K/W		3,32	4,32						2			

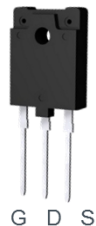
- SiC MOSFET has lower $R_{DS(on)} \cdot \text{Area}$
- Also, Q_g and capacitance are much reduced – for same $R_{DS(on)}$
- High gate resistance of SiC device demands a low-impedance gate drive

Lineup 1700V SiC MOSFET devices:

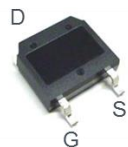
	Part No.	$V_{DS}[V]$	$R_{DSon\ typ}[m\Omega]$ @ $V_{GS}=18V$	$I_D[A]$ @ $T_C=25^\circ C$	$I_D[A]$ @ $T_C=100^\circ C$	$T_{jmax}[^\circ C]$	Package	Die Part No.
	SCT2H12NZ	1700	1150	3,7	2,6	175	TO-3PFM	-
NEW	SCT2H12NY	1700	1150	4,0	2,9	175	TO-268-2L	-
NEW	SCT2750NY	1700	750	5,9	4,0	175	TO-268-2L	-
		1700	100	34	-	175	bare die	S2409



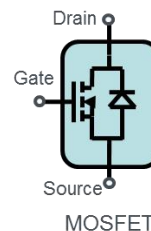
TO-3PFM



TO-268-2L



SCT series



BD768xFJ-LB – Control IC for SiC Aux Supply

Feature

- Optimum System for driving SiC MOSFET
- Quasi – Resonant DC/DC convertor
- Low VCC current (19uA@VCC=18.5V)
- Burst function at light load
- Max Frequency Controlled (120kHz)
- VCC Over Voltage Protection
- VCC Under Voltage Locked Out
- Brown IN/OUT Function
- DC/DC Soft Start
- DC/DC Cycle by Cycle current limiter
- 250nsec Leading-Edge Blanking
- ZT Trigger mask function
- ZT Over Voltage Protection
- Over Load Protection (128ms Timer) ● MASK Function

Specification

- Operating VCC Range : 15.0V ~ 27.5V
- DCDC Max Frequency : 120kHz
- Operating current 800 uA
- Operating Temperature: - 40deg. to +105deg.

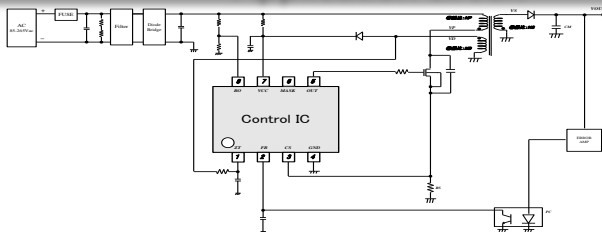
PIN place / Package

NO.	Pin	
1	ZT	Zero Current Detect pin
2	FB	Feedback pin
3	CS	Current Sense pin
4	GND	GND pin
5	OUT	MOSFET drive pin
6	MASK	External TR drive
7	VCC	Power Supply pin
8	BO	Broun IN/OUT monitor pin



SOP-J8S
6.0mm × 4.9mm :
1.27mm pitch
<TYP>

Application circuit



Application

Factory Automation, PV Inverter, Battery Charger

Line up

	FBOLP	VCCOVP
BD7682FJ	AutoRestart	Latch
BD7683FJ	Latch	Latch
BD7684FJ	AutoRestart	AutoRestart
BD7685FJ	Latch	AutoRestart

BD768xFJ-LB – Features for driving SiC MOSFETs



SiC MOSFET gate driving requirement

Compared to Si MOSFETs the **permissible gate-voltage** range is smaller.

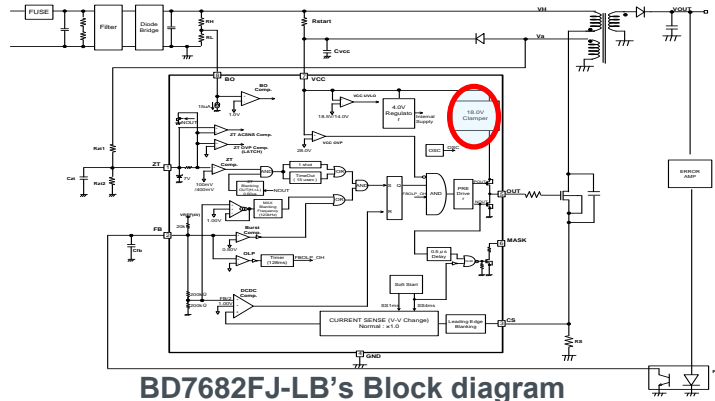
Recommended gate drive voltage for SiC MOSFET: ca. 18V (max. rating: +22V, ensure min. level of ca. 14V to avoid thermal runaway)

Suitable UVLO and gate-clamp circuit integrated in BD768xFJ-LB

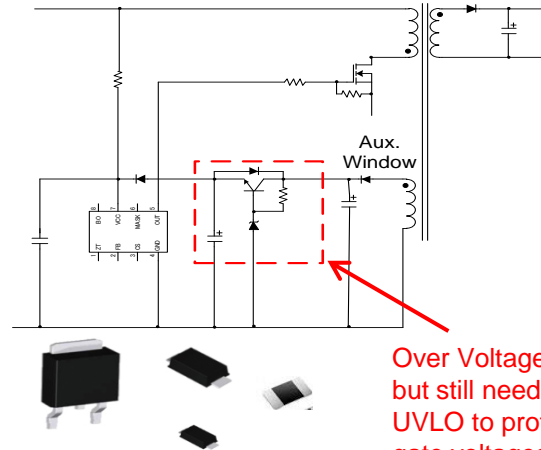
Gate-clamp limits the OUT terminal voltage, so as not to apply an **overvoltage** to the gate voltage of the SiC-MOSFET.

UVLO (14 V typ.) ensures no operation with **undervoltage** to avoid thermal problems.

Parameter	Specifications			Unit
	MIN	TYP	MAX	
OUT Pin Clamp Voltage	16	18	20	V
OUT pin Nch MOS Ron	2	5	10	Ω



BD7682FJ-LB's Block diagram



External Gate Clamp Circuit

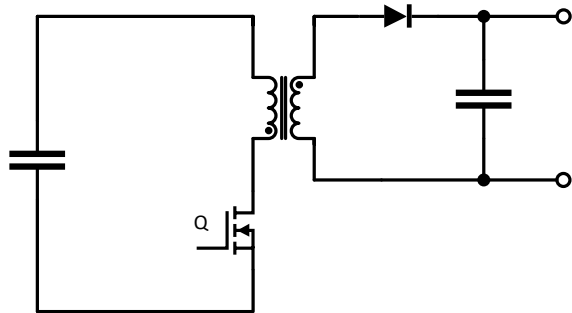
Over Voltage can be prevented, but still need to ensure correct UVLO to protect against too low gate voltages!

Auxiliary power supply solution



SiC-based solution with 1700V MOSFET and single-switch flyback topology

- Single switch
- Isolated package
- Control IC **BD768xFJ**
- Heat sink not mandatory if <40W



TO-268 2L
0.75Ω,
1.15Ω



TO-3PFM
1.15Ω
SCT2H12NZ

Input: 300-900 Vdc
Output: 12 Vdc
Power: 40 W (no heat sink)
Sw. freq.: 90...120 kHz
Efficiency: 85% (300 Vdc), 83% (700 Vdc)

ROHM evaluation board available
BD7682FJ_EVK_301

BD768xFJ



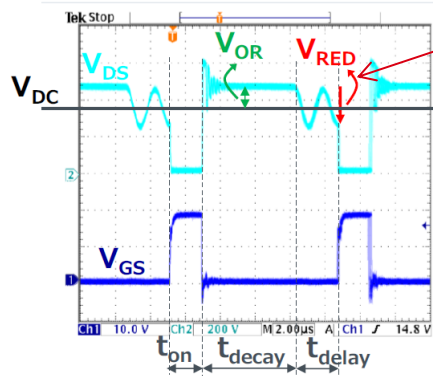
80mm

80mm

Auxiliary power supply solution

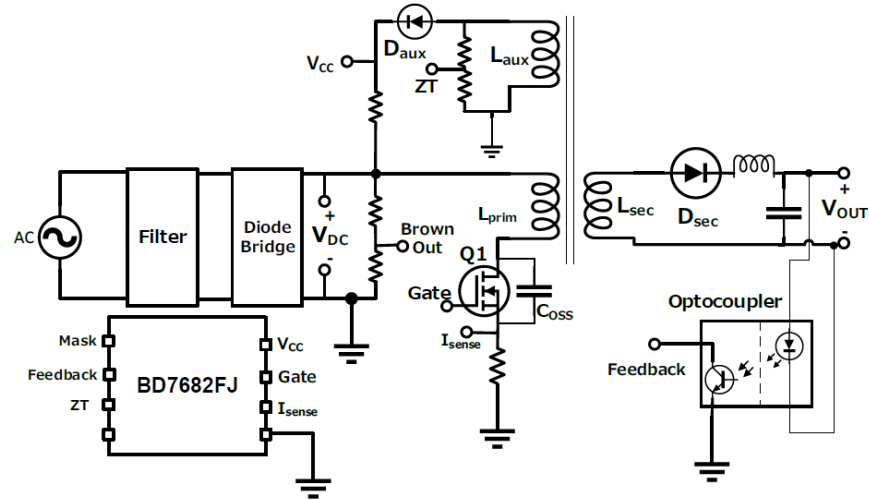
ROHM evaluation board
BD7682FJ_EVK_301

Reduced effective switching voltage leads to lower turn-on loss



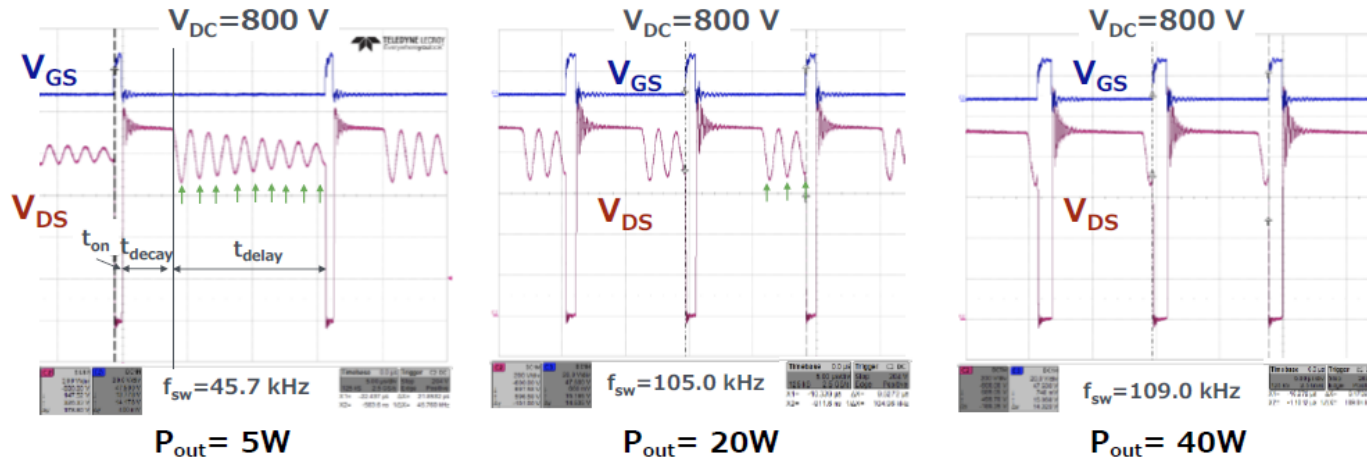
Control IC for SiC based solution: **BD768x FJ**

- Implements quasi-resonant switching to minimise dynamic losses and achieve low noise
- Suitable drive voltage for SiC MOSFET



Auxiliary power supply solution

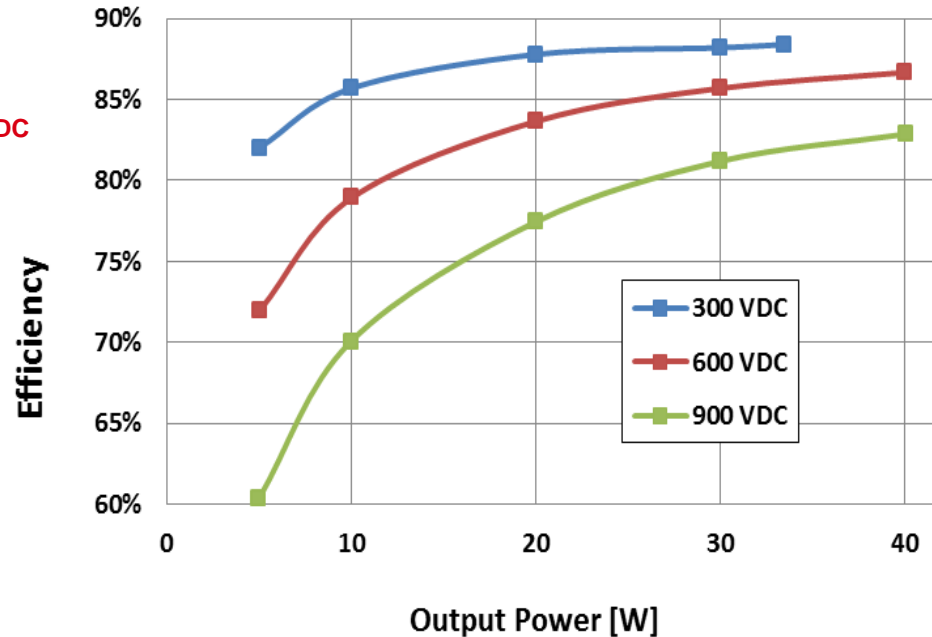
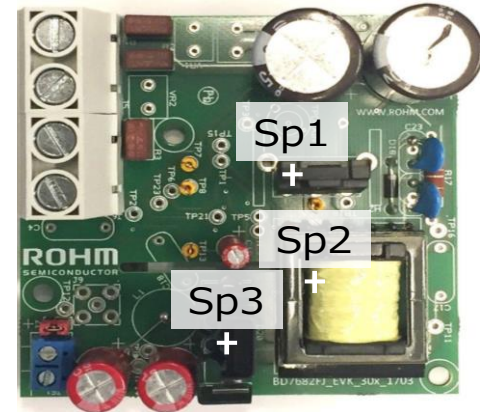
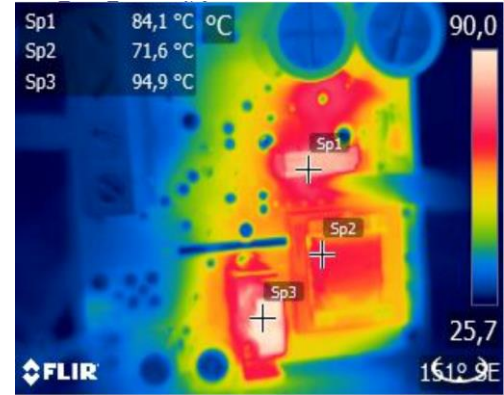
Waveforms of flyback switch for different operating conditions:



- Quasi-resonant operation is maintained across the output power range
- As the delay time decreases the effective switching frequency increases with increased load

Auxiliary power supply solution

Operation at 40W without heat sink →
(with heat sink ca. 100W possible)



- Combination of BD768xFJ and 1700V SiC MOSFET
→ **Simple** and **performant** auxiliary supply solution
- Great alternative to current solutions with series connection of Si MOSFETs or complex topologies.
- Auxiliary supply applications shows that cost advantages can be realised on system level if the SiC device benefits are fully utilised.

Thank you for your attention!



In case of later questions please contact:

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